

Product Change Notice

Exar Corporation

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PRODUCTS AFFECTED:	SP3220EBCA-L/TR	SP3220EBCA-L	SP3220EBEA-L/TR	SP3220EBEA-L
	SP3220ECA-L/TR	SP3220ECA-L	SP3220EEA-L/TR	SP3220EEA-L
	SP3226ECA-L/TR	SP3226ECA-L	SP3226EEA-L/TR	SP3226EEA-L
	SP3227ECA-L/TR	SP3227ECA-L	SP3227EEA-L/TR	SP3227EEA-L
	SP3232EBCA-L/TR	SP3232EBCA-L	SP3232EBEA-L/TR	SP3232EBEA-L
	SP3232ECA-L/TR	SP3232ECA-L	SP3232EEA-L/TR	SP3232EEA-L
	SP3232EUCA-L/TR	SP3232EUCA-L	SP3232EUEA-L/TR	SP3232EUEA-L

CHANGE CATEGORY:

Material	Process	Package
Design	Datasheet	Packing/Shipping
Other: Alternate Foundry and Assembly Site	2	

DESCRIPTION OF CHANGE:

Qualified 0.25um foundry process in TSMC.

Qualified SSOP 16L in Greatek. Both copper and gold wire bonding processes qualified.

IMPACT OF CHANGE:

There is no change to product form, fit or function.

TARGET IMPLEMENTATION DATE: 14-OCTOBER-2014

Please contact customer support (customersupport@exar.com) for sample date availability or qualification data

PROPRIETARY INFORMATION

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